

Please replace the Abstract with the following amended Abstract:

~~The present invention provides an~~ An inductive element and a corresponding method for making an inductive element for surface mounting on an adjacent structure ~~that has~~ for providing improved heat transfer characteristics. Specifically, ~~the present invention includes an inductive element where the~~ a core and winding of the inductive element define coplanar surfaces that can then be mated to an adjacent structure, preferably a printed circuit board. Devices such as inductors or transformers including the ~~inventive~~ inductive element have multiple, low thermal resistance conductive paths for removing heat from the core, and thereby enhance the heat transfer characteristics of the ~~inductive element~~ devices. The inductive element is particularly well suited for power electronics, such as for use as a power choke or as part of a power transformer.